

Developing ANSYS macro for solving Isothermal Reynolds Equation for OCOC boundary condition

Under the guidance of
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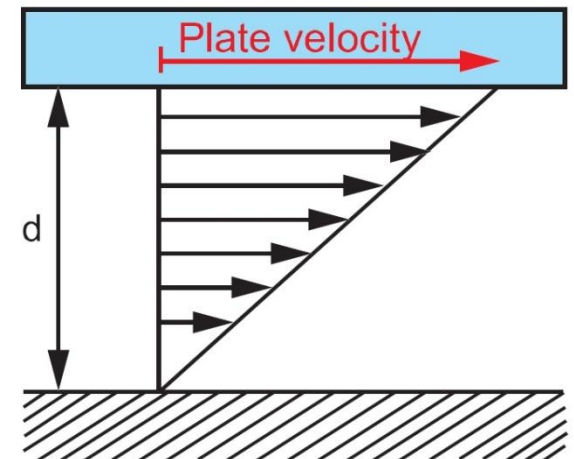
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Presentation Overview

- Introduction
- Governing Equation
- Solving in ANSYS
- Squeeze film analysis
- Modal projection method
- Results

INTRODUCTION

- Thin Film - Small gap of fluid between moving surfaces
 - Squeeze Film Effect
 - Important in accelerometers, micro-torsion mirrors, optical switches, resonators etc.
 - Slide Film Effect
 - Important in comb drives



Governing Equation

- Non Linear Reynolds Equation for compressible film

$$\begin{aligned} & \frac{\partial}{\partial x} \left(\rho \frac{h^3}{\mu} \frac{\partial P}{\partial x} \right) + \frac{\partial}{\partial y} \left(\rho \frac{h^3}{\mu} \frac{\partial P}{\partial y} \right) \\ & = 6 \left\{ 2 \frac{\partial(h\rho)}{\partial t} + \frac{\partial}{\partial x} [\rho h(u_1 + u_2)] + \frac{\partial}{\partial y} [\rho h(v_1 + v_2)] \right\} \end{aligned}$$

- In MEMS, $\frac{\partial}{\partial x} \left(\rho \frac{h^3}{\mu} \frac{\partial P}{\partial x} \right) + \frac{\partial}{\partial y} \left(\rho \frac{h^3}{\mu} \frac{\partial P}{\partial y} \right) = 12 \frac{\partial(h\rho)}{\partial t}$

- For Isothermal condition

$$\frac{\partial}{\partial x} \left(\frac{Ph^3}{\mu} \frac{\partial P}{\partial x} \right) + \frac{\partial}{\partial y} \left(\frac{Ph^3}{\mu} \frac{\partial P}{\partial y} \right) = 12 \frac{\partial(hP)}{\partial t}$$

Contd..

- Non linear Reynolds Equation for squeeze film damping of parallel plates

$$\frac{\partial}{\partial x} \left(P \frac{\partial P}{\partial x} \right) + \frac{\partial}{\partial y} \left(P \frac{\partial P}{\partial y} \right) = \frac{12\mu}{h^3} \frac{\partial(hP)}{\partial t}$$

or

$$\frac{\partial^2}{\partial x^2} P^2 + \frac{\partial^2}{\partial y^2} P^2 = \frac{24\mu}{h^3} \frac{\partial(hP)}{\partial t}$$

Contd..

- Linearized Isothermal Reynolds Equation for compressible gas

$$P_a \left(\frac{\partial^2 p}{\partial x^2} + \frac{\partial^2 p}{\partial y^2} \right) - \frac{12\mu}{h_o^2} \frac{\partial p}{\partial t} = \frac{12\mu p_a}{h_o^3} \frac{dh}{dt}$$

- And finally in the non-dimensional form

$$\left(\frac{\partial^2 \tilde{p}}{\partial \tilde{x}^2} + \frac{\partial^2 \tilde{p}}{\partial \tilde{y}^2} \right) = \sigma \left(\frac{\partial \tilde{h}}{\partial \tau} + \frac{\partial \tilde{p}}{\partial \tau} \right)$$

Squeeze Number $\sigma = \frac{12\mu\omega l^2}{P_a h_o^2}$

Elements in ANSYS for modeling Thin Films

- FLUID 136 and FLUID 138 for squeeze film effects
- FLUID 139 for slide film effects

Conditions to be satisfied to use thin film elements to assess thin film effects

- The governing Reynolds equation limits the application of thin film analyses to structures with lateral dimensions much greater than the gap separation.
- The pressure change across the gap must be much smaller than the ambient (surrounding) pressure.
- Any viscous heating effects must be ignored.

Squeeze Film Analysis

- The fluid film can add stiffening and/or damping to the system depending on the operating frequencies.

- Static Analysis
- Harmonic Analysis

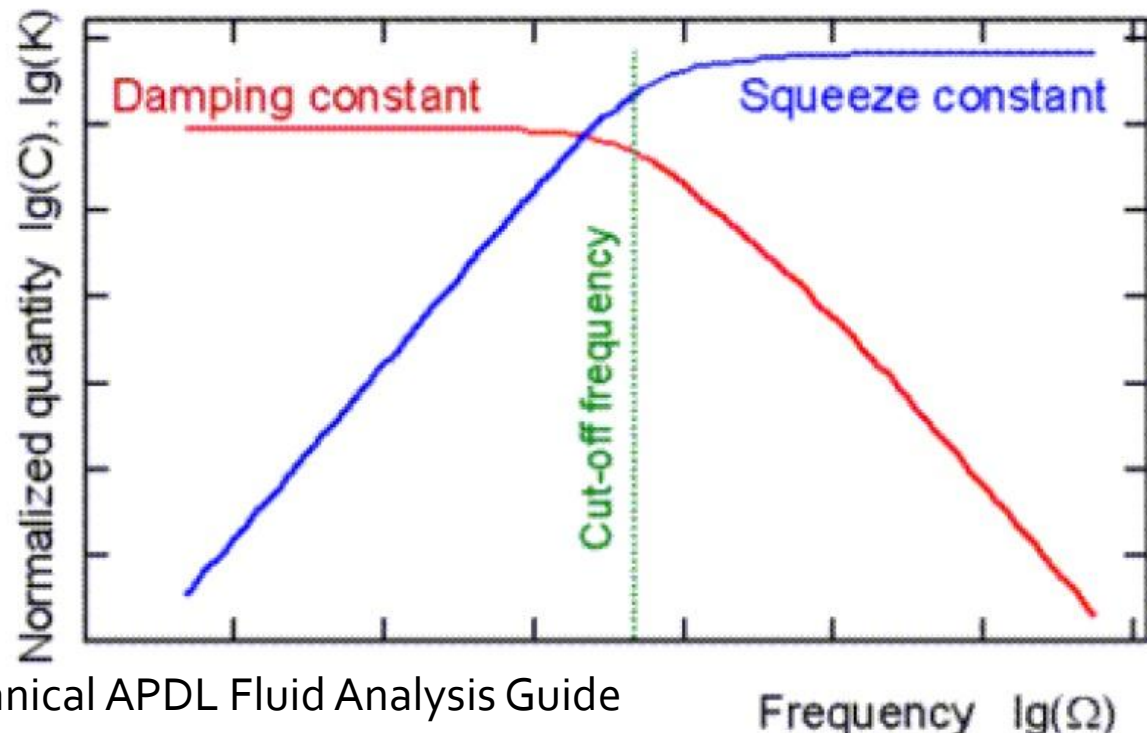


Image taken from ANSYS Mechanical APDL Fluid Analysis Guide

Modal Projection Method

- Fluid is excited by a velocity profile
- Element pressure integrated to compute the element nodal force vector
- Force Vector multiplied for each eigen vector to compute modal forces
- Real and Imaginary parts of modal forces used to compute damping and stiffness coefficients

$$C = \frac{F^{\text{Re}}}{v_z} \quad K = \frac{F^{\text{Im}} \omega}{v_z}$$

- Repeated with next eigen mode

Steps in Computing Damping Parameters

- Build a structural and thin–film fluid model and mesh
- Perform a modal analysis on the structure
- Extract the desired mode eigenvectors
- Select the desired modes for damping parameter calculations
- Perform a harmonic analysis on the thin-film elements
- Compute the modal squeeze stiffness and damping parameters
- Compute modal damping ratio and squeeze stiffness coefficient
- Display the Results

Input Parameters in the ANSYS macro

- Length of the plate = 200 μm
- Width of the plate = 100 μm
- Thickness of the plate = 5 μm
- Air gap = 2 μm
- Ambient Pressure = 0.1 MPa
- Viscosity = 18.3×10^{-12} Kg/ (μm)(s)
- Reference Pressure = 0.1 MPa
- Mean Free Path = 64×10^{-3} μm
- Knudsen Number = Mean Free Path / Air Gap
- Young's Modulus of Silicon = 150 GPa
- Density of Silicon = 2330×10^{-18} Kg/(μm)³
- Poisson's Ratio of Silicon = 0.17

Results – Damping Parameters

- Damping coefficient, Squeeze coefficient, Damping ratio, Stiffness ratio

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File

```
DMPEXT RESULTS
-----
Frequency      Damping coeff  Squeeze coeff.  Damp. ratio  Stiffn. ratio
4621755.      13772.55      0.4082230E+13  0.2371361E-03  0.4840875E-02
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DMPEXT RESULTS
-----
Frequency      Damping coeff  Squeeze coeff.  Damp. ratio  Stiffn. ratio
5949912.      12906.78      0.4013414E+13  0.1726225E-03  0.2871661E-02
```

Thank You